



PATENT
Atty. Dkt. No. AMAT/3778/CMP/CMP/RKK

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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**Group Art Unit: 3723**

**Examiner:** Grant, A.

**Serial No.: 09/728,038**

**Confirmation No.: 2584**

**Filed: December 1, 2000**

**For: Apparatus and Method for Controlling Delivery of Slurry to a Region of a Polishing Device**

RECEIVED

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TECHNOLOGY CENTER R3700

**Assistant Commissioner for Patents  
Washington, D.C. 20231**

**CERTIFICATE OF MAILING**

**37 CFR 1.8**

I hereby certify that this correspondence is being deposited on the date below with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

**Dear Sir:**

6/13/02  
Date

Keith M. Tackett  
Keith M. Tackett

**RESPONSE TO OFFICE ACTION DATED MARCH 15, 2002**

In response to the Office Action dated March 15, 2002, having a shortened statutory period for response set to expire on June 15, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below. The Commissioner is authorized to charge Deposit Account No. 20-0782/3778/CMP/CMP/GGM in the amount of \$174.00, along with any other fees to make this response timely.

### IN THE CLAIMS:

**Please amend the following claims:**

1. (Amended) An apparatus, comprising a semiconductor polishing device having a first surface defining at least two non-intersecting fluid retaining grooves at least a portion of which is oriented at an angle relative to a radial line originating at a center of